

PRM8R9N06CTF

PFC Device Corporation

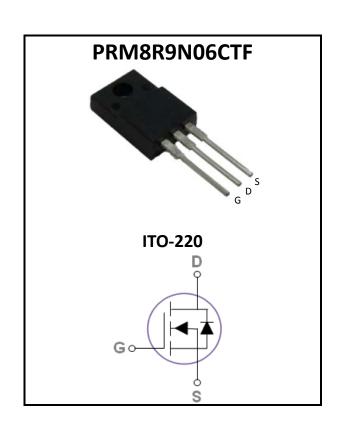
60V Single N-Channel MOSFET

Major ratings and characteristics

Characteristics	Values	Units
V_{DS}	60	V
$I_{D}^{6} (T_{C}=25^{\circ}C)$	51	Α
Max. R _{DS(ON)} @V _{GS} =10V	8.9	mΩ
Max. R _{DS(ON)} @V _{GS} =4.5V	_{N)} @V _{GS} =4.5V 15	
T _J Operating Junction Temperature	-55 to +150	°C

General Description

The N-Channel enhancement mode power field effect transistor is using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. The device is well suited for high efficiency fast switching applications.



Typical Applications

- Charger Adapter
- Power Tools
- LED Lighting

Features

- Max. $R_{DS(ON)}=8.9m\Omega@V_{GS}=10V$
- Improved dv/dt capability
- Fast switching
- 100% E_{AS} Guaranteed
- Green Device Available

1. Characteristics

Maximum Ratings Characteristics

($T_A = 25$ °C unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	±20	V
I _D ⁵	Drain Current – Continuous (T _C =25°C)	51	Α
ID	Drain Current – Continuous (T _C =100°C)	31.4	Α
I _{DM}	Drain Current – Pulsed ¹	204	Α
E _{AS}	Single Pulse Avalanche Energy ²	16	mJ
I _{AS}	Single Pulse Avalanche Current ²	17	Α
ь	Power Dissipation (T _C =25°C)	35.8	W
P _D	Power Dissipation – Derate above 25°C	0.28	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient		62	°C/W
$R_{ heta JC}$	Thermal Resistance Junction to Case		3.5	°C/W



Version 4.0 2 / 8

Electrical Characteristics

(T_J = 25 °C unless otherwise specified)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	60			V
ı	Dunin Course Leakage Current	V _{DS} =60V, V _{GS} =0V, T _J =25°C			1	uA
I _{DSS}	Drain-Source Leakage Current	V _{DS} =48V, V _{GS} =0V, T _J =125°C			100	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA

On Characteristics

R _{DS/(ON)} Static Drain-Source On-Resistance	V _{GS} =10V, I _D =20A		7.5	8.9	$m\Omega$	
$R_{DS(ON)}$		V _{GS} =4.5V, I _D =10A		11	15	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	1.7	2.5	>
g_{fs}	Forward Transconductance	V _{DS} =5V, I _D =20A	1	38		S

Dynamic and switching Characteristics

Q_{q}	Total Gate Charge ^{3,4}		 21.5	
Q_{qs}	Gate-Source Charge ^{3, 4}	V_{DS} =30V, V_{GS} =10V, I_{D} =10A	 3.7	 nC
Q_{gd}	Gate-Drain Charge ^{3, 4}		 5.1	
$T_{d(on)}$	Turn-On Delay Time ^{3, 4}		 7	
T _r	Turn-On Rise Time ^{3, 4}	V_{DD} =30V, V_{GS} =10V, R_{G} =3 Ω	 25	 nc
$T_{d(off)}$	Turn-Off Delay Time ^{3, 4}		 20	 ns
T_f	Turn-Off Fall Time ^{3,4}		 9	
C _{iss}	Input Capacitance		 1241	
C _{oss}	Output Capacitance	V _{DS} =25V, V _{GS} =0V, f=1MHz	 466	 pF
C_{rss}	Reverse Transfer Capacitance		 44	
R_{g}	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	 0.8	 Ω

Drain-Source Diode Characteristics

	V_{SD}	Source to Drain Diode Voltage	V_{GS} =0V, I_{S} =20A	 	1.5	V
	t _{rr}	Reverse Recovery Time	1 20	 15		ns
Ī	Q _{rr}	Reverse Recovery Charge	I _S =20A, di/dt=100A/us	 4		nC

Note:

- 1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
- 2. VDD=50V, VGS=10V, L=0.1mH, RG=25 Ω , Starting TJ=25 $^{\circ}$ C
- 3. The data tested by pulsed, pulse width ≤300us, duty cycle ≤2%.
- 4. Essentially independent of operating temperature.
- 5. Silicon limited

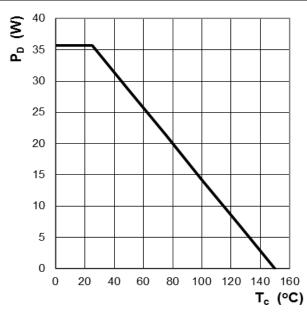


Version 4.0 3 / 8

2. Characteristics Curves

Ratings and Characteristics Curves

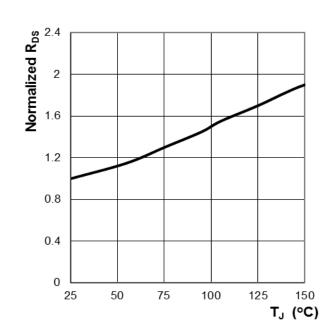
($T_A = 25^{\circ}C$ unless otherwise specified)



₹ 60 40 30 20 10 25 50 75 100 125 150 T_c (°C)

Figure 1: Power Dissipation

Figure 2: Continuous Drain Current vs. T_C



1.4 Normalized V_{GS(th)} 1.2 1 0.8 0.6 0.4 0.2 0 25 50 75 100 125 150 T_J (°C)

Figure 3: Normalized R_{DS(ON)} vs. T_J

Figure 4: Normalized V_{GS(th)} vs. T_J



Version 4.0 4 / 8

Ratings and Characteristics Curves

(T_A = 25° unless otherwise specified)

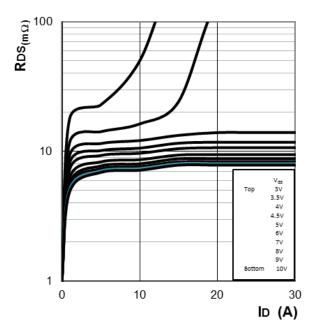


Figure 5: RDS(ON) vs. Drain Current and Gate Voltage

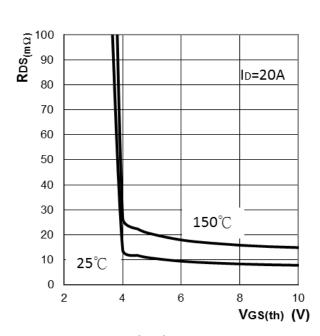


Figure 6: RDS(ON) vs. Gate Voltage

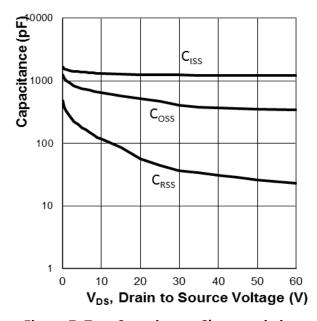


Figure 7: Typ. Capacitance Characteristics

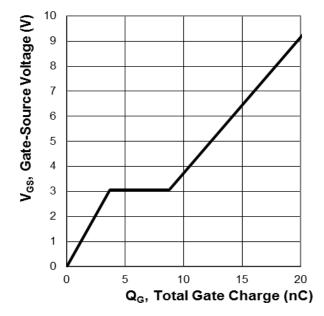


Figure 8: Typ. Gate Charge Characteristics



Version 4.0 5 / 8

Ratings and Characteristics Curves

(T_A = 25° unless otherwise specified)

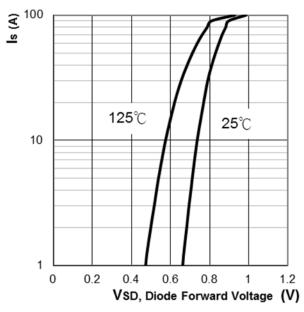


Figure 9: Body Diode Characters
Area

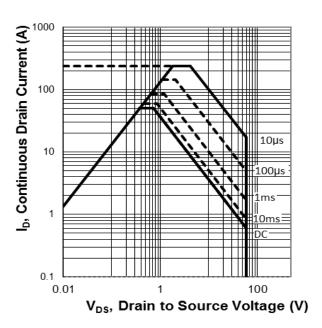


Figure 10: Maximum Safe Operation

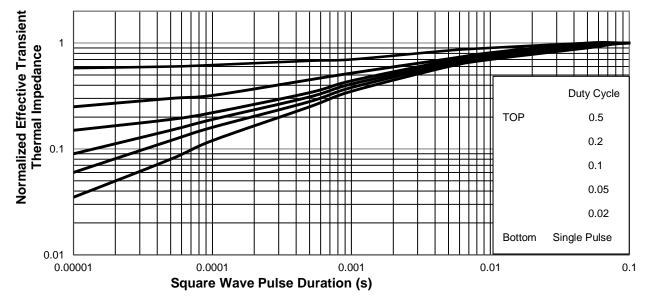


Figure 11: Normalized Thermal Transient Impedance, Junction-to-Case



Version 4.0 6 / 8

3. Marking information

Top Marking Rule

PFC PRM 8R9N06CTF YYWW ABSH PRM8R9N06CTF = Product Type Marking Code

YYWW = Date Code

YY = Last two digits of year

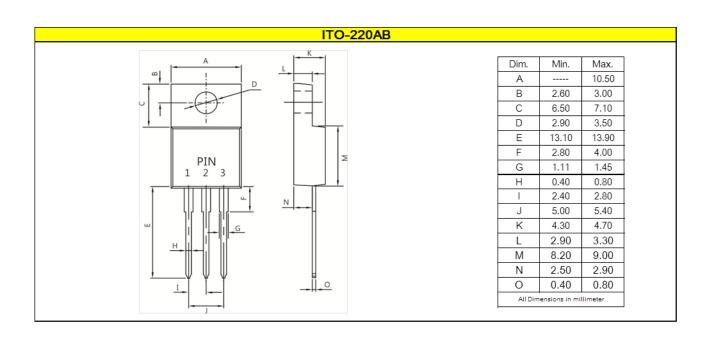
WW = Week code

ABS = Assembly code

H = Halogen Free (N/A = common molding compound)

4. Package information

Package Outline Dimensions millimeters





Version 4.0 7 / 8

5. Ordering information

Part Number	Package	Delivery mode
PRM8R9N06CTF	ITO-220AB	50 pcs / Tube

Mechanical

Molder Plastic: UL Flammability Classification Rating 94V-0
 Device Weight: 0.06 ounces (1.74grams) - ITO-220AB

Mounting Torque : Recommended 4~5 kg-cm

PFC Device Corp reserves the right to make changes without further notice to any products herein. PFC Device Corp makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does PFC Device Corp assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in PFC Device Corp data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typical" must be validated for each customer application by customer's technical experts. PFC Device Corp does not convey any license under its patent rights nor the rights of others. PFC Device Corp products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the PFC Device Corp product could create a situation where personal injury or death may occur. Should Buyer purchase or use PFC Device Corp products for any such unintended or unauthorized application, Buyer shall indemnify and hold PFC Device Corp and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that PFC Device Corp. was negligent regarding the design or manufacture of the part.



Version 4.0 8 / 8